

MM54HC03/MM74HC03 Quad 2-Input Open Drain NAND Gate

General Description

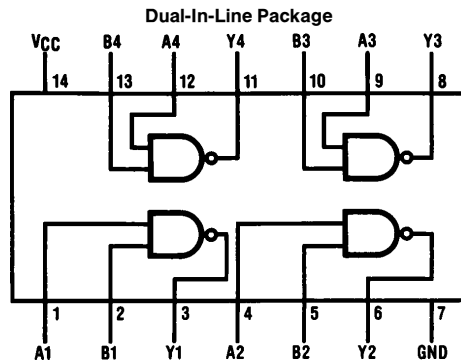
These NAND gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs. All devices have high noise immunity and the ability to drive 10 LS-TTL loads. The 54HC/74HC logic family is functionally as well as pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

As with standard 54HC/74HC push-pull outputs there are diodes to both V_{CC} and ground. Therefore the output should not be pulled above V_{CC} as it would be clamped to one diode voltage above V_{CC} . This diode is added to enhance electrostatic protection.

Features

- Typical propagation delay: 12 ns
- Wide power supply range: 2–6V
- Low quiescent current: 20 μA maximum (74HC Series)
- Low input current: 1 μA maximum
- Fanout of 10 LS-TTL loads

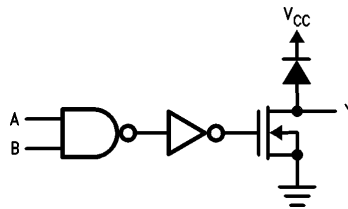
Connection and Logic Diagrams



TL/F/5295-1

Top View

Order Number MM54HC03 or MM74HC03



TL/F/5295-2

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	-0.5 to +7.0V
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$
Clamp Diode Current (I_{IK}, I_{OK})	± 20 mA
DC Output Current, per pin (I_{OUT})	± 25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	± 50 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Power Dissipation (P_D) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temp. (T_L) (Soldering 10 seconds)	260°C

Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temp. Range (T_A)			
MM74HC	-40	+85	°C
MM54HC	-55	+125	°C
Input Rise or Fall Times (t_r, t_f)			
$V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^\circ C$		74HC	54HC	Units
						$T_A = -40$ to $85^\circ C$	$T_A = -55$ to $125^\circ C$	
				Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum Low Level Input Voltage**		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V_{OL}	Minimum Low Level Output Voltage	$V_{IN} = V_{IH}$ $ I_{OUT} \leq 20 \mu A$ $R_L = \infty$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ $ I_{OUT} \leq 4.0$ mA $ I_{OUT} \leq 5.2$ mA	4.5V	0.2	0.26	0.33	0.4	V
			6.0V	0.2	0.26	0.33	0.4	V
I_{LKG}	Maximum High Level Output Leakage Current	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$	6.0V		0.5	5	10	μA
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		± 0.1	± 1.0	± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		2.0	20	40	μA

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

** V_{IL} limits are currently tested at 20% of V_{CC} . The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics $V_{CC}=5V, T_A=25^{\circ}C, C_L=15\text{ pF}, t_r=t_f=6\text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{pZL}, t_{pLZ}	Maximum Propagation Delay	$R_L = 1\text{ K}\Omega$	10	20	ns

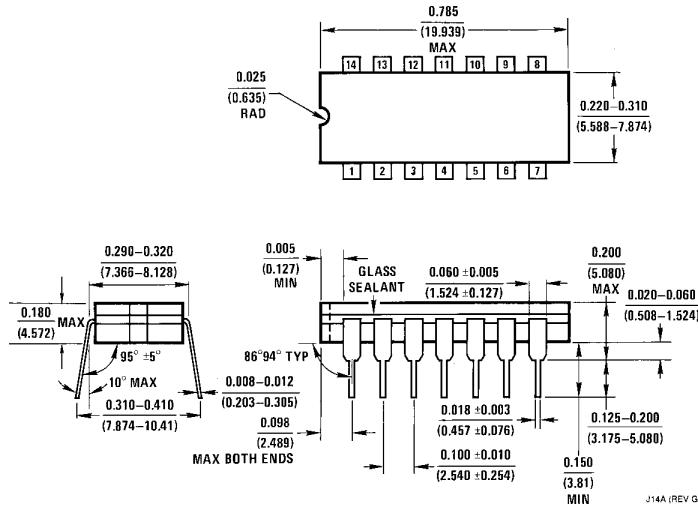
AC Electrical Characteristics

$V_{CC}=2.0V\text{ to }6.0V, C_L=50\text{ pF}, t_r=t_f=6\text{ ns}$ (unless otherwise specified)

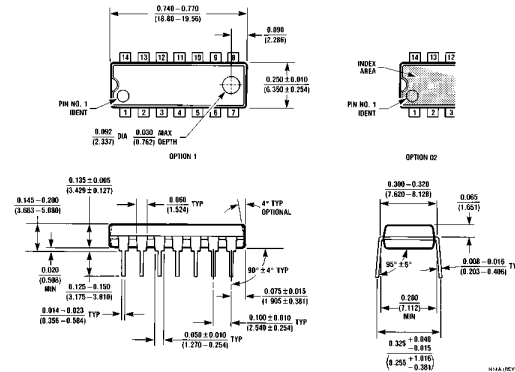
Symbol	Parameter	Conditions	V_{CC}	$T_A=25^{\circ}C$		74HC	54HC	Units
						$T_A=-40\text{ to }85^{\circ}C$	$T_A=-55\text{ to }125^{\circ}C$	
				Typ	Guaranteed Limits			
t_{pLZ}, t_{pZL}	Maximum Propagation Delay	$R_L = 1\text{ K}\Omega$	2.0V	63	125	158	186	ns
			4.5V	13	25	32	37	ns
			6.0V	11	21	27	32	ns
t_{THL}	Maximum Output Fall Time		2.0V	30	75	95	110	ns
			4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		20				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$. The power dissipated by R_L is not included.

Physical Dimensions inches (millimeters)



Ceramic Dual-In-Line Package (J)
Order Number MM54HC03J or MM74HC03J
NS Package Number J14A



Molded Dual-In-Line Package (N)
Order Number MM74HC03N
NS Package Number N14A

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 <p>National Semiconductor Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018</p>	<p>National Semiconductor Europe</p> <p>Fax: (+49) 0-180-530 85 86 Email: cnjwge@tevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tel: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80</p>	<p>National Semiconductor Hong Kong Ltd. 19th Floor, Straight Block, Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960</p>	<p>National Semiconductor Japan Ltd. Tel: 81-043-299-2309 Fax: 81-043-299-2408</p>
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